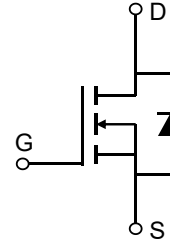


### Description

#### Features

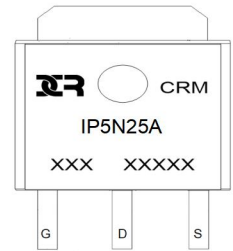
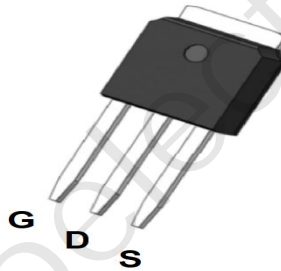
- 250V, 5A  
 $R_{DS(ON)}$  Typ = 468mΩ @  $V_{GS} = 10V$   
 Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- 100% UIS TESTED!
- 100%  $\Delta V_{ds}$  TESTED!



Schematic Diagram

#### Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

#### Package Marking and Ordering Information

Device	Marking	Package	Outline	TUBE(pcs)	Inner Box (pcs)	Per Carton (pcs)
CRMIP5N25A	CRMIP5N25A	TO-251-3L	TUBE	72	4320	21600

#### Absolute Maximum Ratings (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Units
$V_{DS}$	Drain-to-Source Voltage	250	V
$V_{GS}$	Gate-to-Source Voltage	±30	V
$I_D$	Continuous Drain Current	$T_C = 25^\circ\text{C}$	5 A
		$T_C = 100^\circ\text{C}$	3 A
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>	20	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>(2)</sup>	120	mJ
$P_D$	Power Dissipation	$T_C = 25^\circ\text{C}$	31.25 W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	4	°C/W
$T_J, T_{STG}$	Junction & Storage Temperature Range	-55 to 150	°C

### Electrical Characteristics ( $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
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#### Off Characteristics

$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	250	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 250\text{V}, V_{GS} = 0\text{V}$	-	-	1.0	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 30\text{V}$	-	-	$\pm 100$	nA

#### On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2.5	3	3.5	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance <sup>(3)</sup>	$V_{GS} = 10\text{V}, I_D = 2.5\text{A}$	-	468	562	mΩ

#### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 25\text{V},$ $f = 1\text{MHz}$	-	465	-	pF
$C_{oss}$	Output Capacitance		-	68	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	10	-	pF
$Q_g$	Total Gate Charge	$V_{GS} = 0 \text{ to } 10\text{V}$ $V_{DS} = 200\text{V}, I_D = 5\text{A}$	-	10	-	nC
$Q_{gs}$	Gate Source Charge		-	3	-	nC
$Q_{gd}$	Gate Drain("Miller") Charge		-	5.2	-	nC

#### Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{GS} = 10\text{V}, V_{DD} = 150\text{V}$ $I_D = 5\text{A}, R_{GEN} = 25\Omega$	-	6	-	ns
$t_r$	Turn-On Rise Time		-	25	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	22	-	ns
$t_f$	Turn-Off Fall Time		-	24	-	ns

#### Drain-Source Diode Characteristics and Max Ratings

$I_S$	Maximum Continuous Drain to Source Diode Forward Current	$V_{GS} = 0\text{V}, I_S = 2.5\text{A}$	-	-	5	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current		-	-	20	A
$V_{SD}$	Drain to Source Diode Forward Voltage		-	-	1.2	V
$t_{rr}$	Body Diode Reverse Recovery Time		-	423	-	ns
$Q_{rr}$	Body Diode Reverse Recovery Charge		-	4.3	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
2.  $E_{AS}$  condition: Starting  $T_J = 25^\circ\text{C}$ ,  $V_{DD} = 100\text{V}$ ,  $V_G = 10\text{V}$ ,  $R_G = 25\Omega$ ,  $L = 10\text{mH}$ ,  $I_{AS} = 4.9\text{A}$
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 0.5\%$ .

## Test Circuit

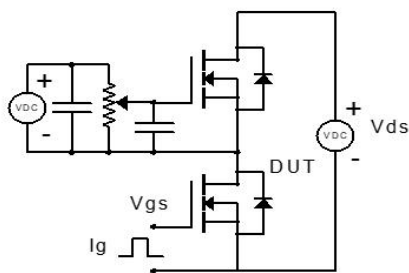


Figure 1: Gate Charge Test Circuit & Waveform



Figure 2: Resistive Switching Test Circuit & Waveform

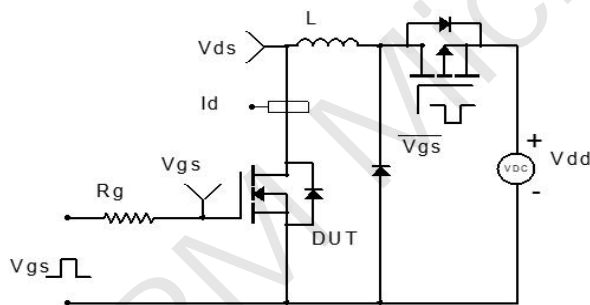


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

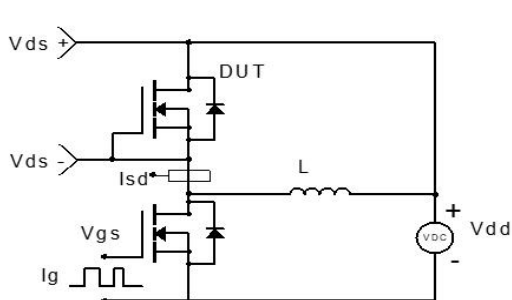
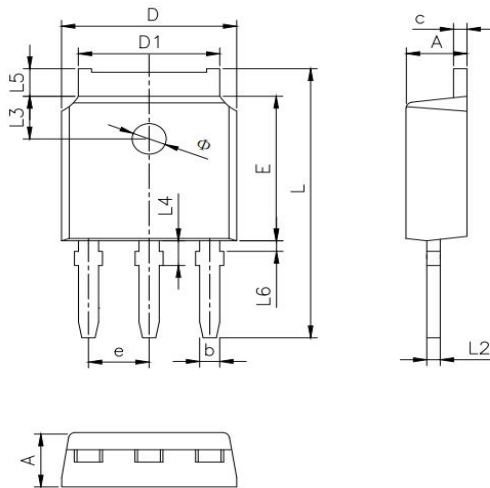


Figure 4: Diode Recovery Test Circuit & Waveform

### Package Mechanical Data(TO-251-3L)




SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	2.20	2.30	2.40
b	0.66	0.76	0.86
c	0.46	0.51	0.58
D	6.50	6.60	6.70
D1	5.10	5.33	5.46
D2	4.83 REF.		
E	6.00	6.10	6.20
e	2.19	2.29	2.39
L	11.02	11.22	11.42
L1	4.10 REF.		
L2	0.508BSC		
L3	1.80 REF.		
L4	0.95	1.05	1.15
L5	0.90	—	1.25
L6	0.15	—	0.75
Φ	1.10	—	1.30
V	5.40 REF.		

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